


# MATERIAL DECLARATION SHEET

**BOURNS®**

Material Number	CRN1206 Series			
Product Line	Fixed Resistors			
Compliance Date	08/05/2025			
RoHS Compliant	Yes	MSL	1	

No.	Construction Element(subpart)	Homogeneous Material	Material weight [mg]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Ceramic	Substrate	8.588	Aluminum oxide	1344-28-1	96	79.672	82.992
				Silicon dioxide	14808-60-7	2	1.66	
				Magnesium oxide	1309-48-4	2	1.66	
2	Top conductor	Copper	0.034	Copper	7440-50-8	85	0.28	0.329
				None-lead Glass	65997-18-4	15	0.049	
3	Bottom conductor	Copper	0.2916	Copper	7440-50-8	85	2.395	2.818
				None-lead Glass	65997-18-4	15	0.423	
4	Resistance layer	Copper alloy	0.2648	Copper	7440-50-8	55	1.407	2.559
				Nickel	7440-02-0	35	0.896	
				None-lead Glass	65997-18-4	10	0.256	
5	First encapsulating	Glass	0.0851	None-lead Glass	65997-18-4	100	0.822	0.822

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6	Overcoat	Resin	0.2731	Epoxy Resin	25036-25-3	100	2.639	2.639
7	Side conductor	NiCr	0.2341	Nickel	7440-02-0	56	1.923	2.262
				Chromium	7440-47-3	44	0.339	
8	Ni Plating	Nickel	0.1985	Nickel	7440-02-0	100	1.918	1.918
9	Sn Plating	Tin	0.3573	Tin	7440-31-5	100	3.453	3.453
10	Marking	Resin	0.0215	Polymer	29690-82-2	70	0.146	0.208
				Titanium dioxide	1317-80-2	30	0.062	
		Total weight	10.348					

**This Document was updated on: 08/05/2025**

**Important remarks:**

1. It is the responsibility of the user to verify they are accessing the latest version.
  - a. "Compliance Date" is not the date supplier submits the MDS, but when the product was first compliant with RoHS.
  - b. "This Document was updated on:" is where we indicate when supplier submits the MDS. All previous MDS must be archived for traceability in the future.
  - c. Material weights for components less than 100mg (most Semiconductor products) should be listed in milligrams. This avoids all those zeros and round off issues.